

ABSTRACT

A light emitting die package and a method of making the light emitting die package are disclosed. The die package includes a stem substrate having grooves, a wire lead attached to the grooves, and a light emitting diode (LED) mounted on the stem substrate. Also coupled to the substrate are a sleeve, a reflector, and a lens. To make the light emitting die package, a long substrate is formed and wire leads attached to the substrate. Then, the substrate including the attached wire leads is cut to predetermine lengths to form individual stem substrates. To each stem substrate, LED, reflector, and lens are coupled.